What is claimed is:

1. A substrate for circuit wiring, in which an electronic component is mounted by soldering to a wiring pattern formed on an insulated layer deposited over a metallic substrate, wherein

a mounting portion of said electronic component is resin-molded with a resin material having a coefficient of linear thermal expansion smaller than the coefficient of linear thermal expansion of said insulated layer.

2. A substrate for circuit wiring as claimed in claim 1, wherein said insulated layer is formed from a resin material containing an inorganic filler for increasing heat dissipation and an elastic filler for reducing an elastic modulus.

3. A substrate for circuit wiring as claimed in claim 1 or 2, wherein the coefficient of linear thermal expansion of said resin material for said resin-molding is adjusted by adding an inorganic filler to said molding resin.

4. A substrate for circuit wiring as claimed in claim 3, wherein said inorganic filler has electrical insulation properties and high thermal conductivity.

5. A substrate for circuit wiring as claimed in claim 4, wherein said inorganic filler comprises one or more materials selected from the group consisting of silicon oxide, aluminum oxide, aluminum nitride, silicon nitride, and boron nitride.

6. A substrate for circuit wiring as claimed in claim 5, wherein said metallic substrate is aluminum based.

7. A substrate for circuit wiring as claimed in claim 1 or 2, wherein the mounting portion of said electronic component is molded with said resin material with said insulated layer and said metallic substrate in integral fashion.

8. A substrate for circuit wiring as claimed in

claim 7, wherein said inorganic filler has electrical insulation properties and high thermal conductivity.

9. A substrate for circuit wiring as claimed in claim 8, wherein said inorganic filler comprises one or more materials selected from the group consisting of silicon oxide, aluminum oxide, aluminum nitride, silicon nitride, and boron nitride.

10. A substrate for circuit wiring as claimed in claim 9, wherein said metallic substrate is aluminum based.